

Amendments to the claims:

This listing of claims will replace all prior versions and listing, of claims in the application:

Listing of Claims:

Claims 1 and 2 (canceled).

Claim 3 (currently amended): A photosensitive resin composition in the form of an aqueous emulsion ~~according to claim 1~~ further comprising:

(A) an emulsion of a photosensitive water-insoluble polymer, the emulsion being obtained by reacting (i) an aqueous polymer emulsion which contains a water-insoluble polymer as its main component and which contains a polymer having a hydroxyl group with (ii) an N-alkylol(meth)acrylamide;

(B) at least one monomer having at least one photoreactive ethylenically unsaturated group;

(C) a photopolymerization initiator; and

(E) an epoxy compound having at least two epoxy groups per molecule.

Claim 4 (currently amended): A photosensitive resin composition according to claim [1] 3 wherein the component (B) comprises a monomer (b) having at least one carboxyl group and at least one photoreactive ethylenically unsaturated group in a molecule.

Claims 5-10 (canceled)

Claim 11 (currently amended): A method for producing a screen printing stencil comprising:

- (I) a step of providing a photosensitive resin composition according to ~~any one of claims 1-4~~ claim 3 or 4;
- (II) a step of forming a film of the photosensitive resin composition on a releasable film;
- (III) a step of selectively exposing the film to form a cured film;
- (IV) a step of washing away to remove a non-exposed portion of the film; and
- (V) a step of transferring the resulting cured film onto a screen.

Claims 12-14 (canceled).

Claim 15 (currently amended): A method for producing a printed wiring board produced by using the photosensitive resin composition according to claim ~~14~~ 3 or 4 comprising:

- (I) a step of providing a substrate having a metallic layer formed on its surface;
- (II) a step of applying the photosensitive resin composition to the surface of the substrate and then drying it;
- (III) a step of selectively exposing a predetermined portion of the photosensitive resin composition which is applied to the substrate to form a cured film;
- (IV) a step of washing away to remove the non-exposed portion of the photosensitive resin

composition;

(V) a step of immersing the substrate in an etching solution to subject a part of the metallic layer to be etched; and

(VI) a step of removing the cured film.

Claim 16 (currently amended): A method for producing a printed wiring board produced by using the photosensitive resin composition according to claim 14 3 or 4 comprising:

(I) a step of providing a substrate with a conductive circuit formed on its surface;

(II) a step of applying the photosensitive resin composition to the surface of the substrate and then drying it;

(III) a step of selectively exposing a predetermined portion of the photosensitive resin composition which is applied to the substrate to form a cured film; and

(IV) a step of washing away to remove the non-exposed portion of the photosensitive resin composition.

Claim 17 (original): A method for producing a printed wiring board according to claim 16 further comprising a step of heating the cured film to obtain a permanent protective coating.

Claim 18 (currently amended): A printed wiring board with a cured film on its surface, the cured film being made from the photosensitive resin composition according to ~~any one of claims~~

[1-] claim 3 or 4.

Claim 19 (original): A printed wiring board according to claim 18 wherein the cured film is a permanent protective coating.

Claims 20-23 (canceled).